

Technical Data Sheet

MODEL NO: 195UR/ANB4 1.60x1.5x0.8mm CHIP LED

Features:

- Package in 8mm tape on 7" diameter reel
- Compatible with automatic placement equipment
- Compatible with reflow solder process

Applications:

- Indicators
- Automotive: backlighting in dashboard and switch
- Backlight for LCD

Dice material	Emitted color	Lens Color
AlGaInP	Red	
		Water transparent
InGaN	Blue	

Electrical/Optical Characteristics(Ta=25°C)

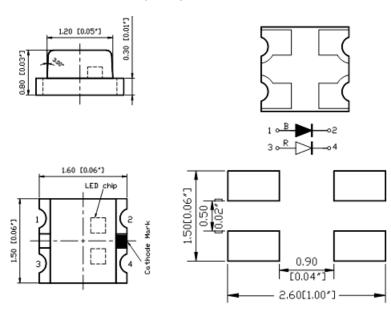
Parameter	Test	Symbol		Value			l lmit
	Condition			Min	Тур	Max	Unit
Spectral half bandwidth	I==5mA	Δλ	R		20		nm
			В		30		
Dominant wavelength	IF=5mA	λD	R	620	620	630	- nm
			В	465	470	475	
Forward voltage	I _F =5mA	VF	R		2.0	2.5	V
			В		3.3	3.8	
Luminous intensity	I==5mA	lv	R	30			- mcd
			В	40			
Viewing angle at 50% lv	IF=10mA	2 0 1/2	R	140			Deg
			В		140		
Reverse current	V _R =5V	l _R	R	- 10		μА	
			IR B				



Absolute Maximum Ratings(Ta=25℃)

Parameter	Symbol	Va	Unit	
		R	В	
Power dissipation	Pd	75	114	mW
Forward current	lF	;	mA	
Reverse voltage	VR		V	
Operating temperature range	Тор	-40	$^{\circ}\!\mathbb{C}$	
Storage temperature range	Tstg	-40	$^{\circ}\!\mathbb{C}$	
Peak pulsing current (1/8 duty f=1kHz)	lfp	1	mA	

PACKAGING DIMENSIONS (mm):



Precautions For Use:

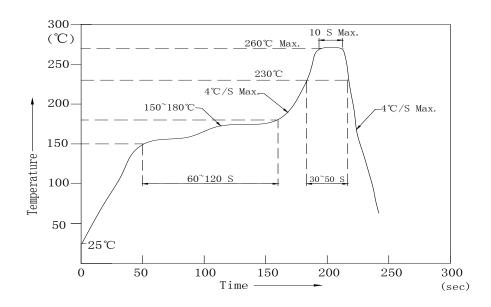
Over - current - proof

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen)

Storage

- 1. The operation of temperature and R.H. are : 5° C $\sim 30^{\circ}$ C, 60%R.H. Max.
- 2. Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a dampproof box with desiccating regent. Considering the tape life, we suggest our customers to use our products within 1.5 year (from production date).
- 3. It's recommended to bake before soldering when the package is unsealed after 72 hrs. The condition is : $60^{\circ}\text{C}\pm5^{\circ}\text{C}$ for 15hrs.

■ Reflow Temp/Time



NOTES:

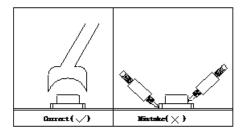
- 1. We recommend the reflow temperature $245^{\circ}\text{C}(\pm 5^{\circ}\text{C})$.the maximum soldering temperature should be limited to 260°C .
- 2. dont cause stress to the epoxy resin while it is exposed to high temperature.
- 3. Number of reflow process shall be 2 times or less.

■Soldering iron

Basic spec is \leq 5sec when 260°C. If temperature is higher, time should be shorter (+10°C \rightarrow -1sec). Power dissipation of iron should be smaller than 20W, and temperatures should be controllable. Surface temperature of the device should be under 230°C.

■Rework

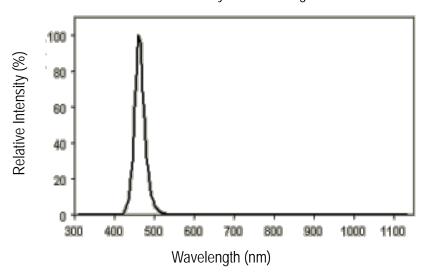
- 1. Customer must finish rework within 5 sec under 260° C.
- 2. The head of iron can not touch copper foil
- 3. Twin-head type is preferred.

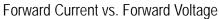


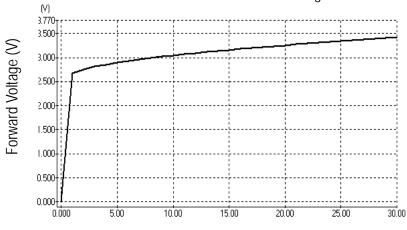
■ Avoid rubbing or scraping the resin by any object, during high temperature, for example reflow \ solder etc.

■ OPTICAL CHARACTERISTIC CURVES

Relative Intensity vs. Wavelength

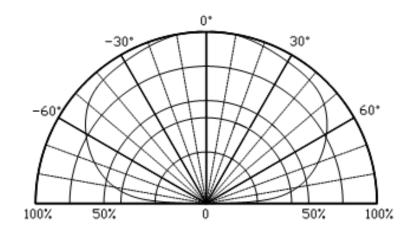




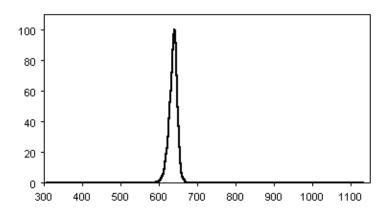


Forward Current (mA)

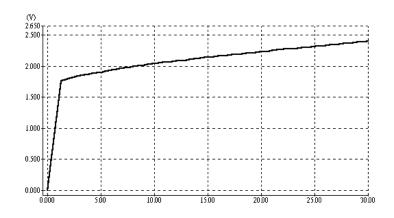
Directive Characteristics



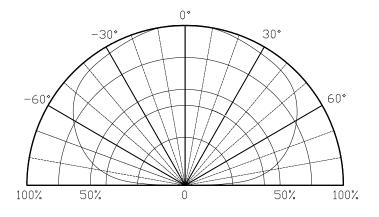
Relative Intensity vs. Wavelength



Forward Current vs. Forward Voltage



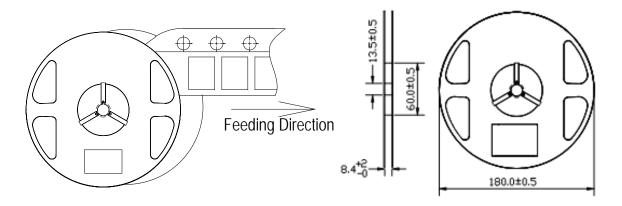
Directive Characteristics



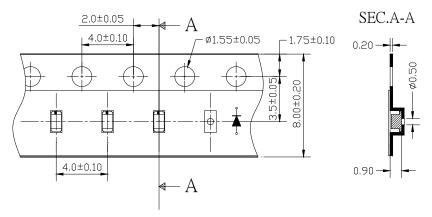


- Packaging Specifications
- Feeding Direction

• Dimensions of Reel (Unit: mm)



• Dimensions of Tape (Unit: mm)



Arrangement of Tape

